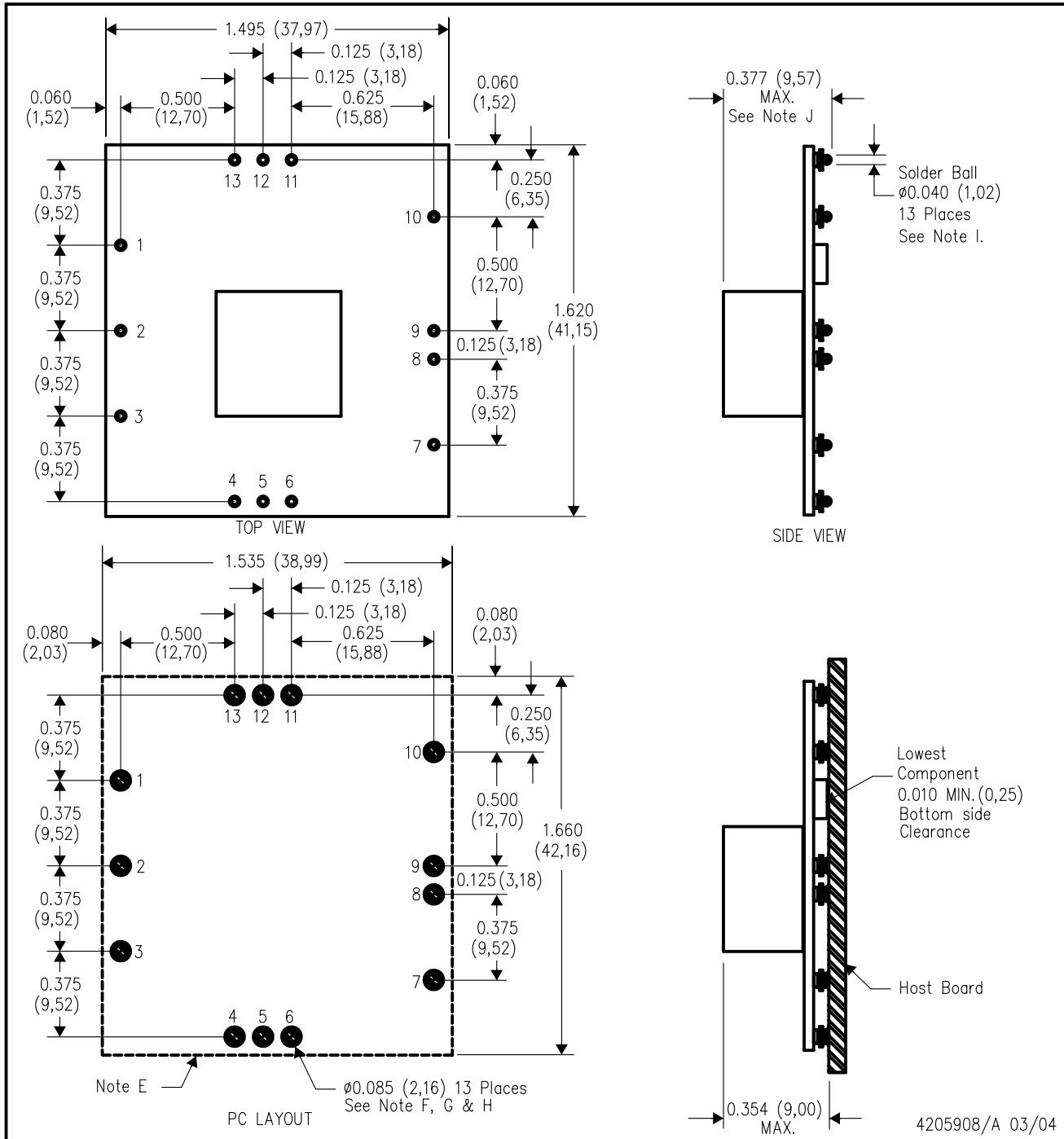


EUQ (R-PDSS-B13)

DOUBLE SIDED MODULE



NOTES:

- A. All linear dimensions are in inches (mm).
- B. This drawing is subject to change without notice.
- C. 2 place decimals are ± 0.030 (± 0.76 mm).
- D. 3 place decimals are ± 0.010 (± 0.25 mm).
- E. Recommended keep out area for user components.
- F. Power pin connection should utilize four or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).

- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16).
Paste screen thickness: 0.006 (0,15).
- H. Pad type: Solder mask defined.
- I. All pins: Material – Copper Alloy
Finish – Tin (100%) over Nickel plate
Solder Ball – See product data sheet.
- J. Dimension prior to reflow solder.

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

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